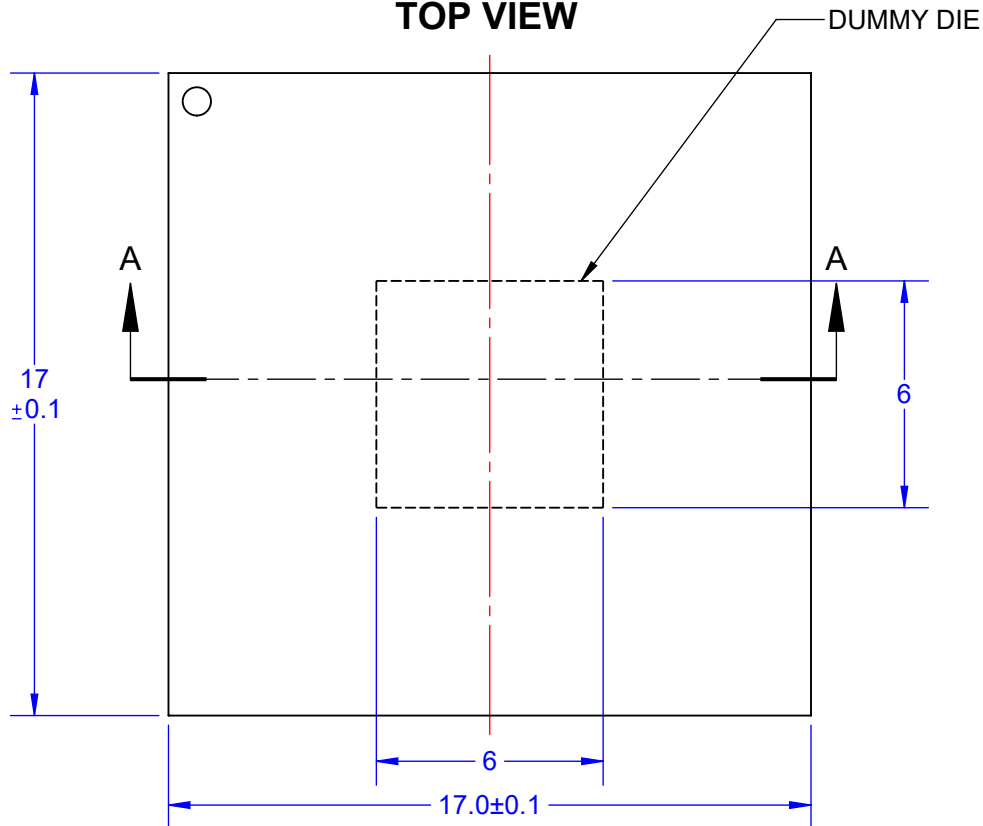
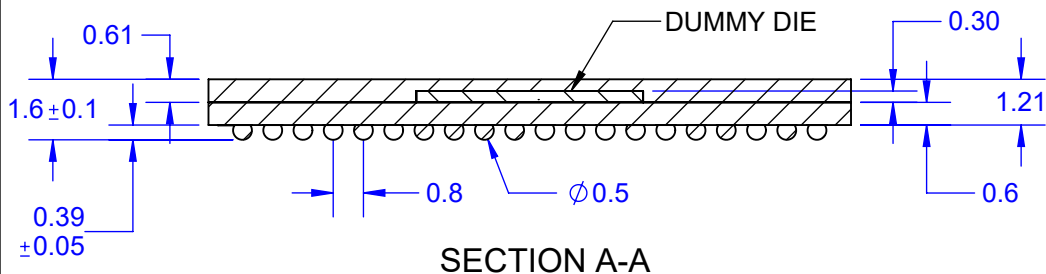
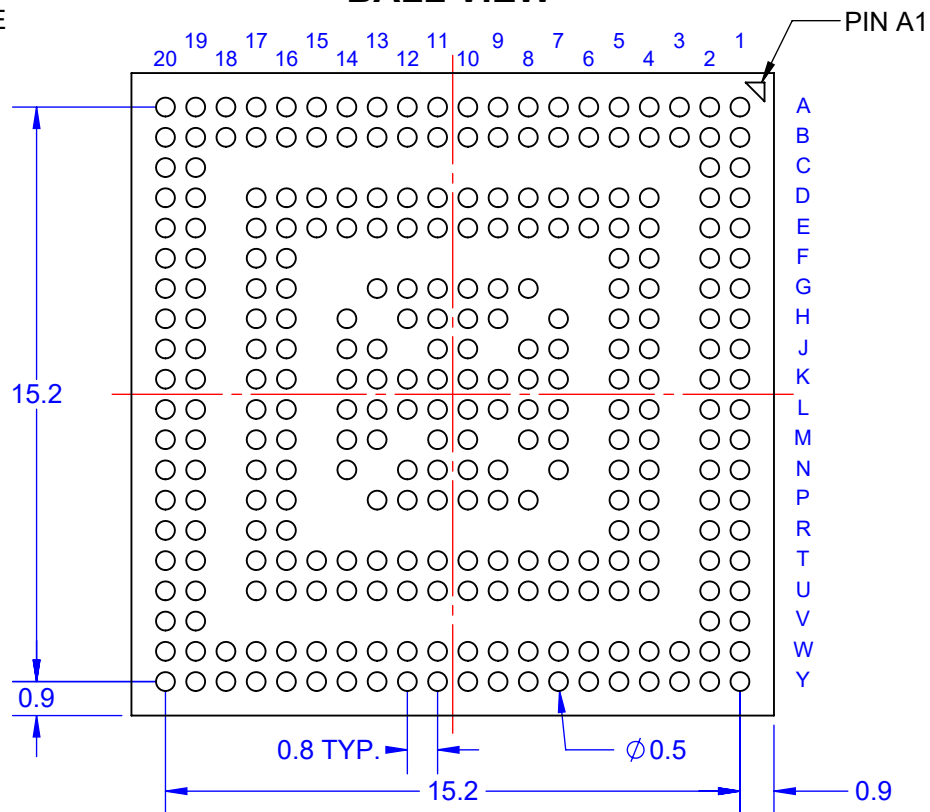


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

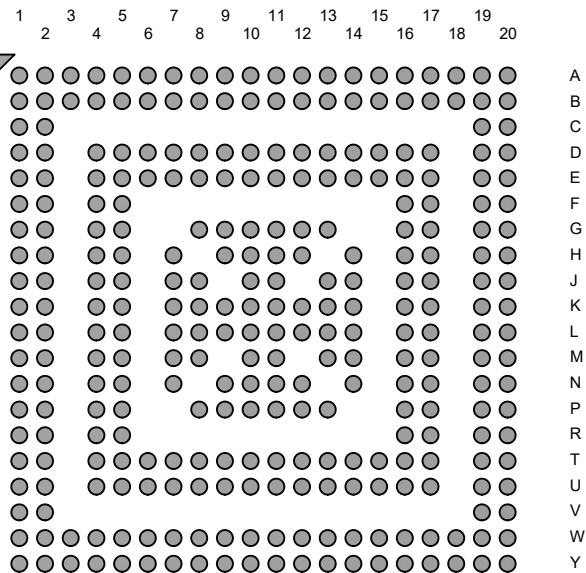
- 1) DIMENSIONS: mm.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): φ 0.50mm (19.7mil).
- 4) SOLDER MASK DEFINED PAD OPENING: φ 0.406mm (16mil).
- 5) PAD Cu DIAMETER: φ 0.50mm (19.7mil).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) PAD PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA292T.8C-D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA292T.8-D	Sn63/Pb37	Sn63	NO	YES

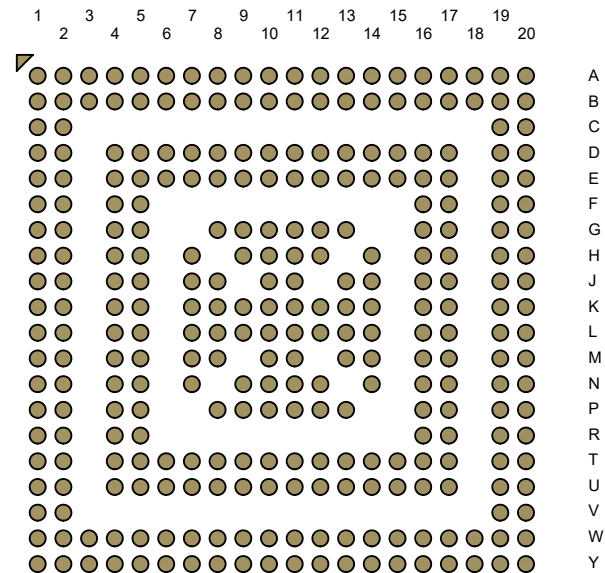
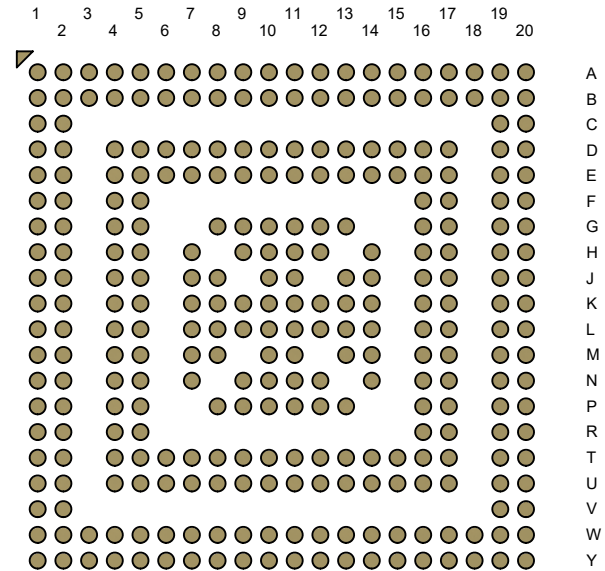
APPROVALS	DATE	TopLine®			
DRAWN T. Au	4/13/2023	TITLE BGA292T.8-D DUMMY BGA			
ENG M. Hart	4/13/2023				
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		5:1	A	582015	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

BALL VIEW



TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)



AFTER MOUNTING

Notes:

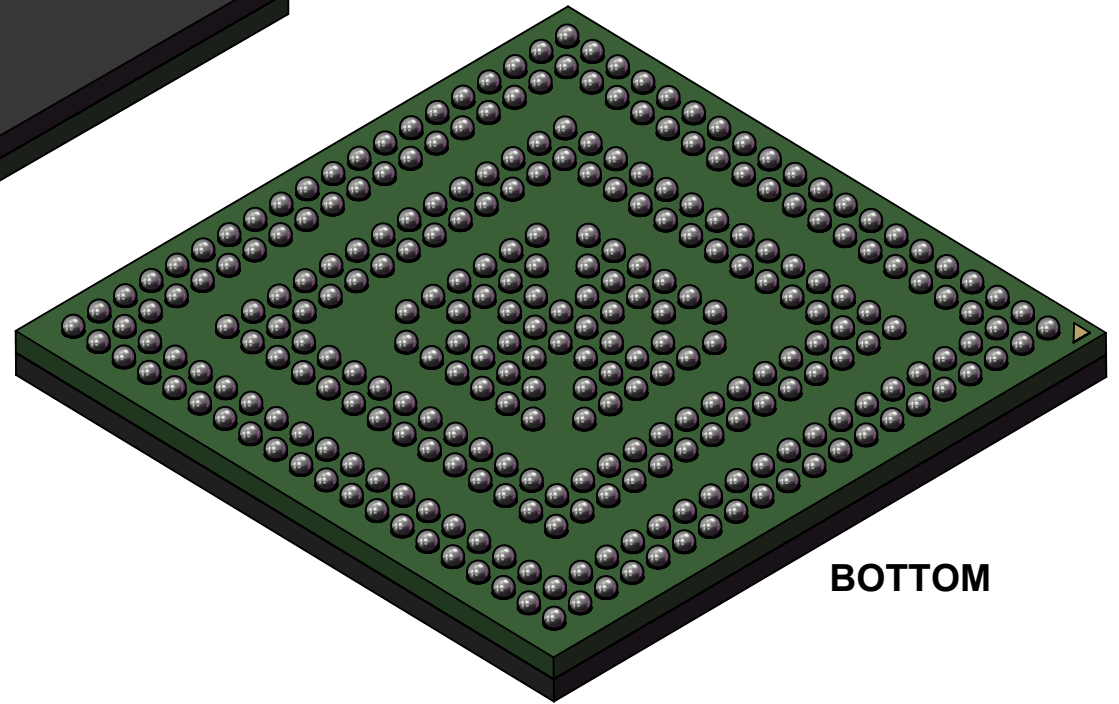
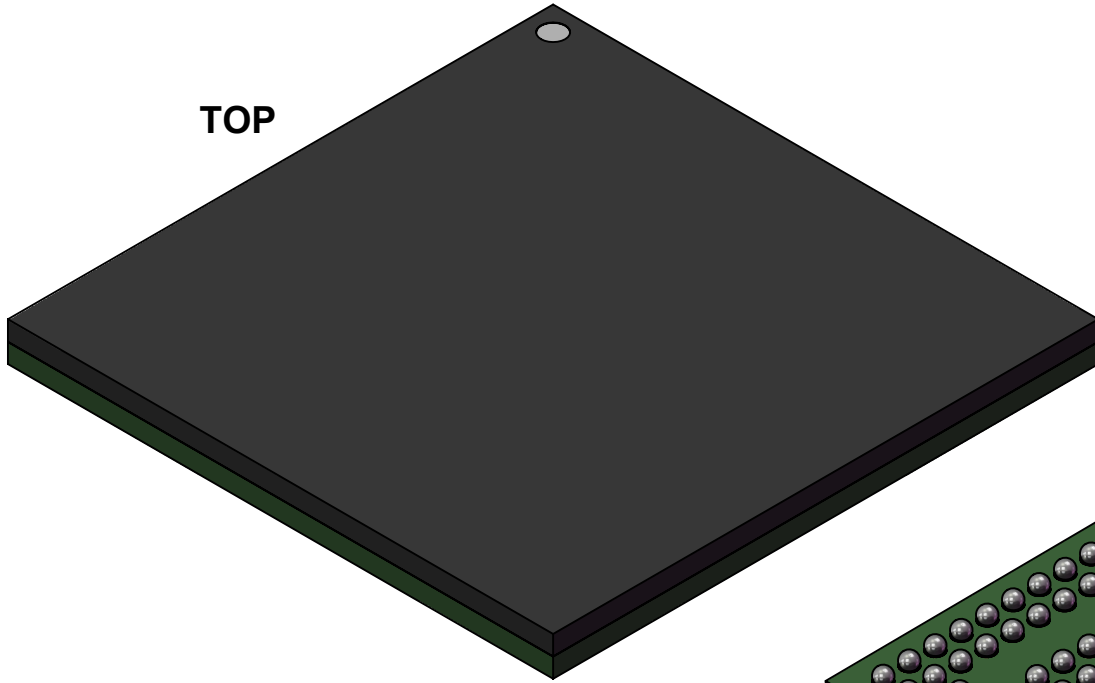
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER ϕ 0.50mm (19.7mil).
- 3) PCB TRACING LINE WIDTH 0.150 [6mil].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING ϕ 0.406mm (16mil).



TITLE				BGA292T.8-D DUMMY BGA			
SCALE	SIZE	DRAWING NO.		REV			
4.25:1	A	582015		A			
DO NOT SCALE DRAWING						SHEET 2 OF 3	

MODEL

TOP



BOTTOM

TopLine[®]

TITLE BGA292T.8-D
DUMMY BGA

SCALE 6:1	SIZE A	DRAWING NO. 582015	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3